

1.8V，可编程电阻器 温度开关和SC70内的 模拟输出温度传感器

 查询样品: **TMP300B-Q1**

特性

- 准确度: $\pm 1^{\circ}\text{C}$ (+25°C时的典型值)
- 可编程跳变点
- 可编程滞后: $5^{\circ}\text{C}/10^{\circ}\text{C}$
- 开漏电路输出
- 低功率: $110\mu\text{A}$ (最大值)
- 宽电压范围: **+1.8V 至 +18V**
- 运行温度: -40°C 至 $+150^{\circ}\text{C}$
- 模拟输出: $10\text{mV}/^{\circ}\text{C}$
- **SC70-6** 封装

应用范围

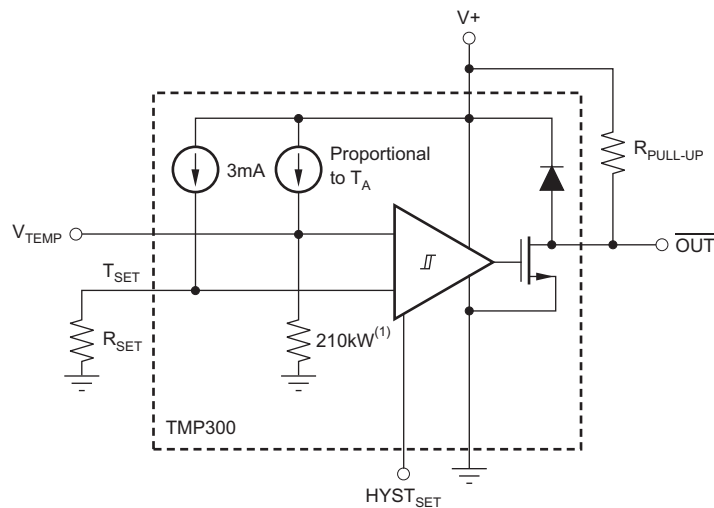
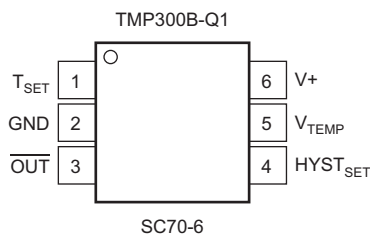
- 符合汽车应用要求
- 电源系统
- **DC-DC**模块
- 过热监控
- 电子保护系统

说明

TMP300B-Q1是一款低功率，电阻器可编程，数字输出温度开关。通过添加一个外部电阻器它可设定一个阈值点。提供2级滞后。TMP300B-Q1有一个 V_{TEMP} 模拟输出，此输出能被用做一个测试点或者被用于温度补偿环路。

因其电源电压低至1.8V并且流耗较低，TMP300B-Q1非常适合对于电源要求较高的应用。

采用具有经证实的热特性的2个微封装，为需要简单和可靠温度管理的用户提供完整的和简单的解决方案。



NOTE: (1) Thinfilm resistor with approximately 10% accuracy; however, this accuracy error is trimmed out at the factory.



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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ORDERING INFORMATION⁽¹⁾

ORDERABLE P/N	T _A	PACKAGE	TOP SIDE SYMBOL
TMP300BQDCKRQ1 or TMP300B-Q1	-40°C to 125°C	SC70 - DCK Reel of 3000	SBG

(1) For the most current package and ordering information see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

		VALUE	UNIT
Supply Voltage	V+	+18	V
Signal Input Terminals, Voltage ⁽²⁾		-0.5 to (V+) + 0.5	V
Signal Input Terminals, Current ⁽²⁾		±10	mA
Output Short-Circuit ⁽³⁾	I _{sc}	Continuous	
Open-Drain Output		(V+) + 0.5	V
Operating Temperature	T _A	-40 to +150	°C
Storage Temperature	T _A	-55 to +150	°C
Junction Temperature	T _J	+150	°C
ESD Rating	Human Body Model (HBM)	4000	V
	Charged Device Model (CDM)	1000	V
	Machine Model (MM)	200	V

- (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not supported.
- (2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current limited to 10mA or less.
- (3) Short-circuit to ground.

ELECTRICAL CHARACTERISTICS

At $V_S = 3.3V$ and $T_A = -40^\circ C$ to $+125^\circ C$, unless otherwise noted.

PARAMETER	TEST CONDITIONS	TMP300B-Q1			UNIT	
		MIN	TYP	MAX		
TEMPERATURE MEASUREMENT						
Measurement Range	$V_S = 2.35V$ to $18V$	-40		+125	$^\circ C$	
	$V_S = 1.8V$ to $2.35V$	-40		$100 \times (V_S - 0.95)$	$^\circ C$	
TRIP POINT						
Total Accuracy	$T_A = -40^\circ C$ to $+125^\circ C$		± 2	± 6	$^\circ C$	
R_{SET} Equation	T_C is in $^\circ C$	$R_{SET} = 10 (50 + T_C)/3$			$k\Omega$	
HYSTERESIS SET INPUT						
LOW Threshold ⁽¹⁾				0.4	V	
HIGH Threshold ⁽¹⁾		$V_S - 0.4$			V	
Threshold Hysteresis	$HYST_{SET} = GND$		5		$^\circ C$	
	$HYST_{SET} = V_S$		10		$^\circ C$	
DIGITAL OUTPUT						
Logic Family			CMOS			
Open-Drain Leakage Current ⁽¹⁾	$OUT = V_S$			10	μA	
Logic Levels						
V_{OL}	$V_S = 1.8V$ to $18V$, $I_{SINK} = 5mA$			0.3	V	
ANALOG OUTPUT						
Accuracy			± 2	± 5	$^\circ C$	
Temperature Sensitivity			10		$mV/^\circ C$	
Output Voltage ⁽¹⁾	$T_A = +25^\circ C$	720	750	780	mV	
V_{TEMP} Pin Output Resistance			210		$k\Omega$	
POWER SUPPLY						
Quiescent Current ⁽²⁾	I_Q , $V_S = 1.8V$ to $18V$, $T_A = -40^\circ C$ to $+125^\circ C$			110	μA	
TEMPERATURE RANGE						
Specified Range	T_A	$V_S = 2.35V$ to $18V$	-40		+125	$^\circ C$
		$V_S = 1.8V$ to $2.35V$	-40		$100 \times (V_S - 0.95)$	$^\circ C$
Operating Range	T_A	$V_S = 2.35V$ to $18V$	-40		+150	$^\circ C$
		$V_S = 1.8V$ to $2.35V$	-50		$100 \times (V_S - 0.95)$	$^\circ C$
Thermal Resistance	θ_{JA}					
SC70				250	$^\circ C/W$	
SOT23-6				180	$^\circ C/W$	

(1) Specified by design. Not production tested.

(2) See [Figure 1](#) for typical quiescent current.

TYPICAL CHARACTERISTICS

At $V_S = 5V$, unless otherwise noted.

QUIESCENT CURRENT OVER TEMPERATURE AND SUPPLY

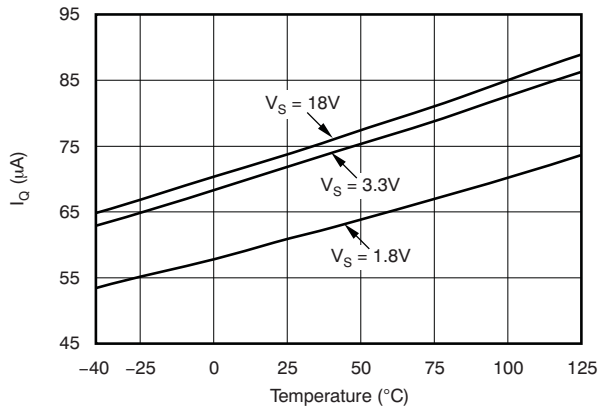


Figure 1.

R_{SET} SHIFT DUE TO R_{SET} TOLERANCE

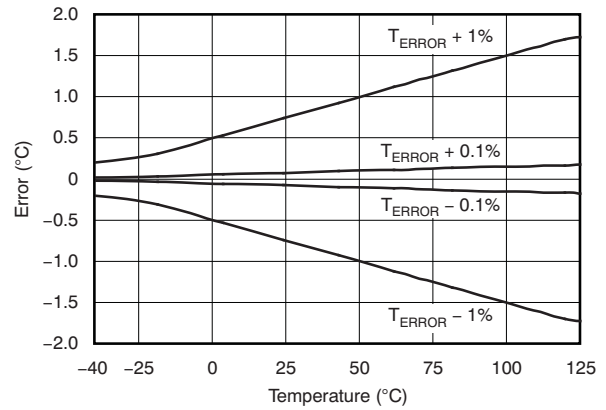


Figure 2.

R_{SET} VS TEMPERATURE

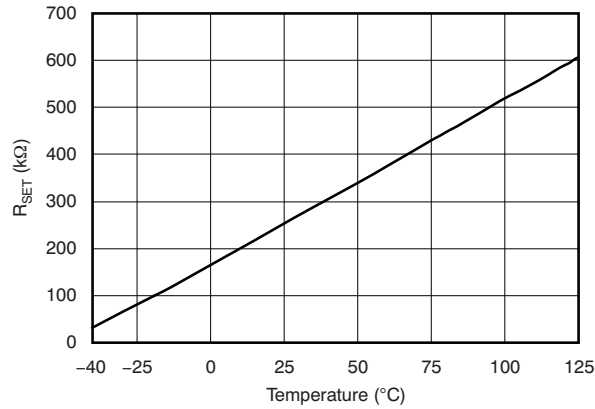


Figure 3.

TYPICAL TRIP ERROR

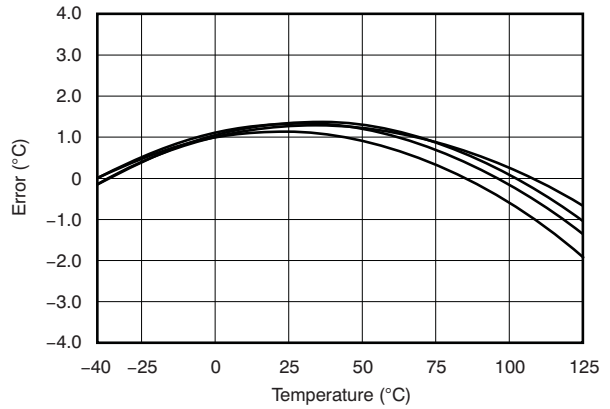


Figure 4.

TYPICAL ANALOG OUTPUT ERROR

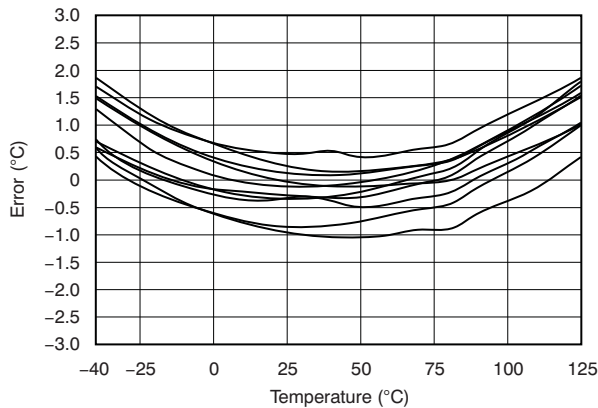


Figure 5.

ANALOG PSR OVER TEMPERATURE

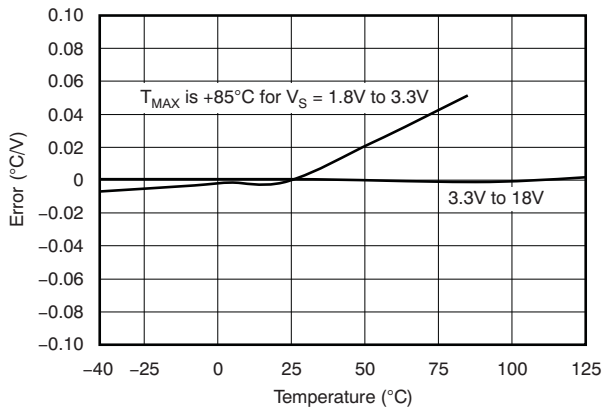
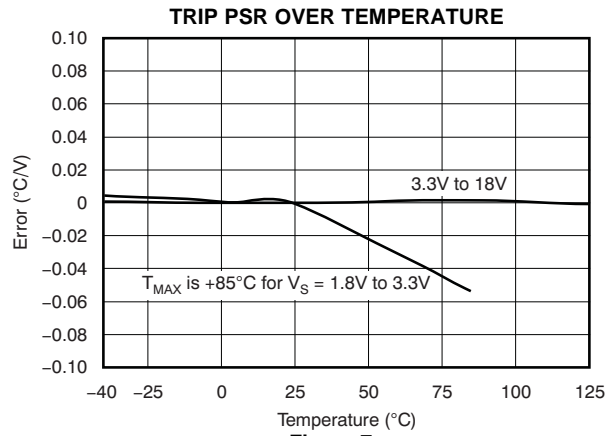


Figure 6.

TYPICAL CHARACTERISTICS (continued)

At $V_S = 5V$, unless otherwise noted.



APPLICATIONS INFORMATION

The TMP300B-Q1 is a thermal sensor designed for over-temperature protection circuits in electronic systems. The TMP300B-Q1 uses a set resistor to program the trip temperature of the digital output. An additional high-impedance (210kΩ) analog voltage output provides the temperature reading.

CALCULATING R_{SET}

The set resistor (R_{SET}) provides a threshold voltage for the comparator input. The TMP300B-Q1 trips when the V_{TEMP} pin exceeds the T_{SET} voltage. The value of the set resistor is determined by the analog output function and the 3μA internal bias current.

To set the TMP300B-Q1 to trip at a preset value, calculate the R_{SET} resistor value according to Equation 1 or Equation 2:

$$R_{SET} = \frac{(T_{SET} \times 0.01 + 0.5)}{3e^{-6}} \tag{1}$$

Where T_{SET} is in °C; or

$$R_{SET} \text{ in } k\Omega = \frac{10(50 + T_{SET})}{3} \tag{2}$$

Where T_{SET} is in °C.

USING V_{TEMP} TO TRIP THE DIGITAL OUTPUT

The analog voltage output can also serve as a voltage input that forces a trip of the digital output to simulate a thermal event. This simulation facilitates easy system design and test of thermal safety circuits, as shown in Figure 8.

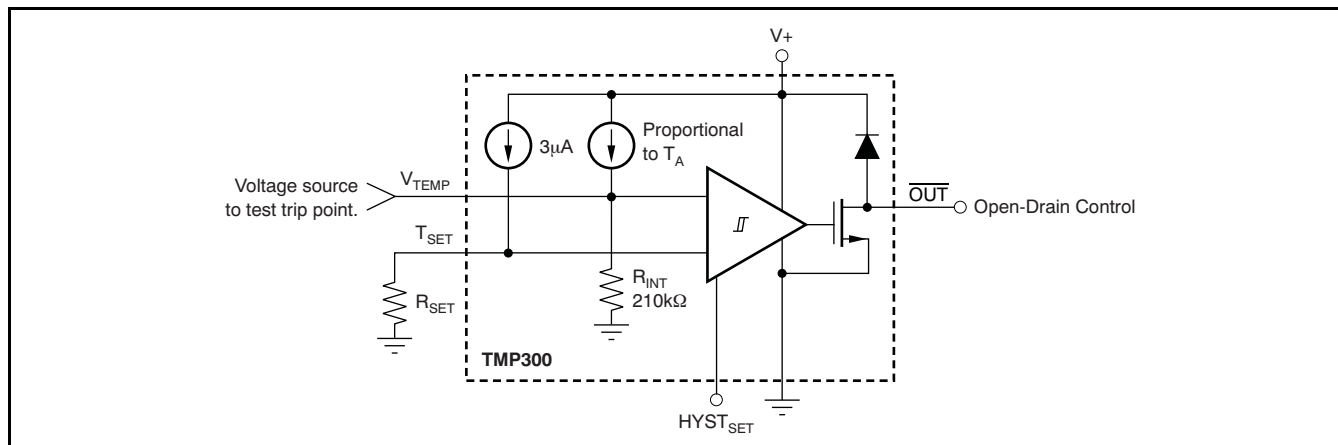


Figure 8. Applying Voltage to Trip Digital Output

ANALOG TEMPERATURE OUTPUT

The analog out or V_{TEMP} pin is high-impedance (210k Ω). Avoid loading this pin to prevent degrading the analog out value or trip point. Buffer the output of this pin when using it for direct thermal measurement. Figure 9 shows buffering of the analog output signal.

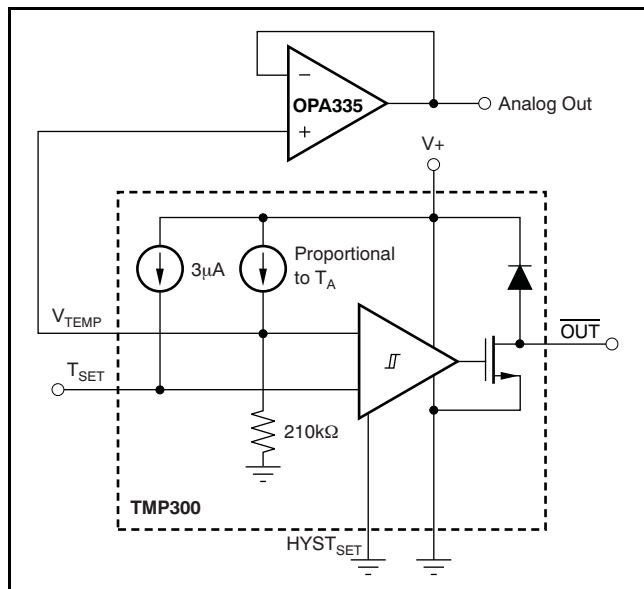


Figure 9. Buffering the Analog Output Signal

USING A DAC TO SET THE TRIP POINT

The trip point is easily converted by changing the digital-to-analog converter (DAC) code. This technique can be useful for control loops where a large thermal mass is being brought up to the set temperature and the \overline{OUT} pin is used to control the heating element. The analog output can be monitored in a control algorithm that adjusts the set temperature to prevent overshoot. Trip set voltage error versus temperature is shown in Figure 10, which shows error in $^{\circ}\text{C}$ of the comparator input over temperature. An alternative method of setting the trip point by using a DAC is shown in Figure 11.

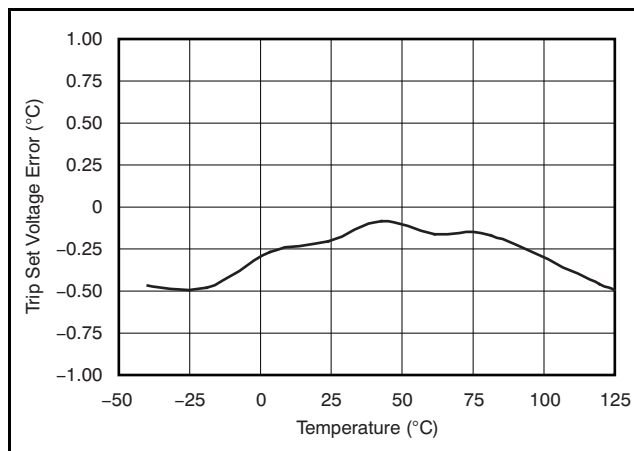


Figure 10. Trip Set Voltage Error vs Temperature

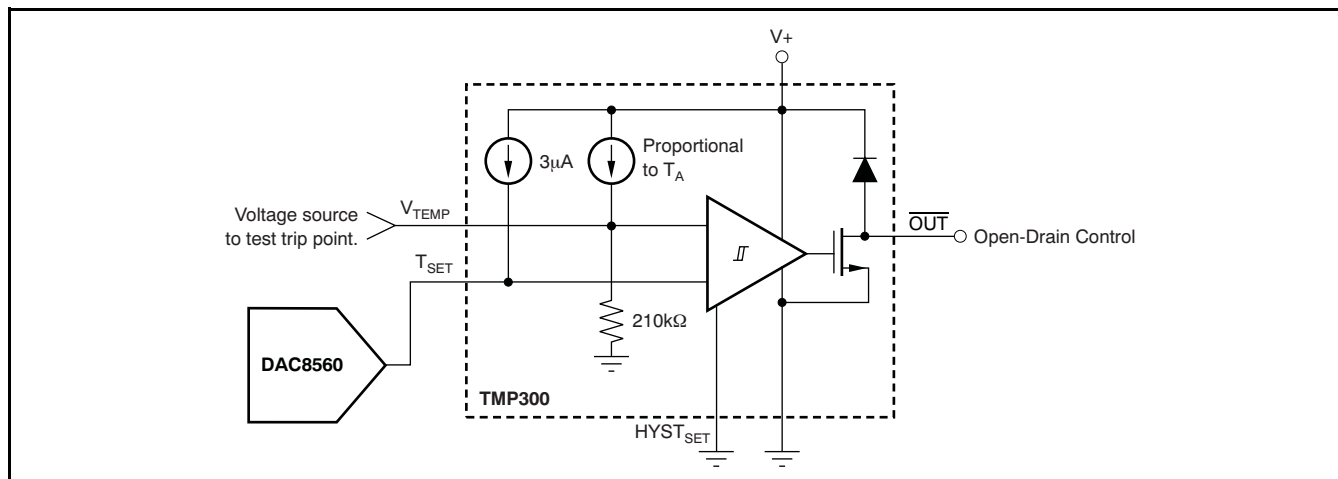


Figure 11. DAC Generates the Voltage-Driving T_{SET} Pin

HYSTERESIS

The hysteresis pin has two settings. Grounding HYST_{SET} results in 5°C of hysteresis. Connecting it to V_S results in 10°C of hysteresis. Hysteresis error variation over temperature is shown in Figure 12 and Figure 13.

Bypass capacitors should be used on the supplies as well as on the R_{SET} and analog out (V_{TEMP}) pins when in noisy environments, as shown in Figure 14. These capacitors reduce premature triggering of the comparator.

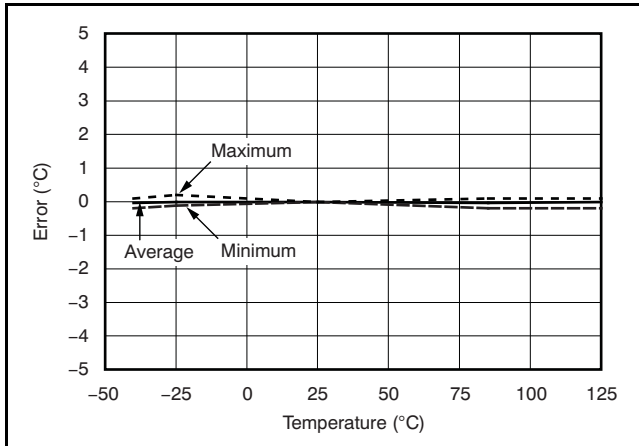


Figure 12. 5°C Hysteresis Error vs Temperature

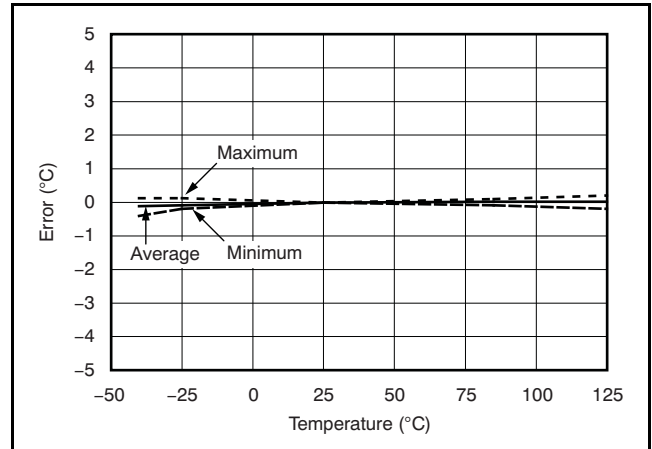


Figure 13. 10°C Hysteresis Error vs Temperature

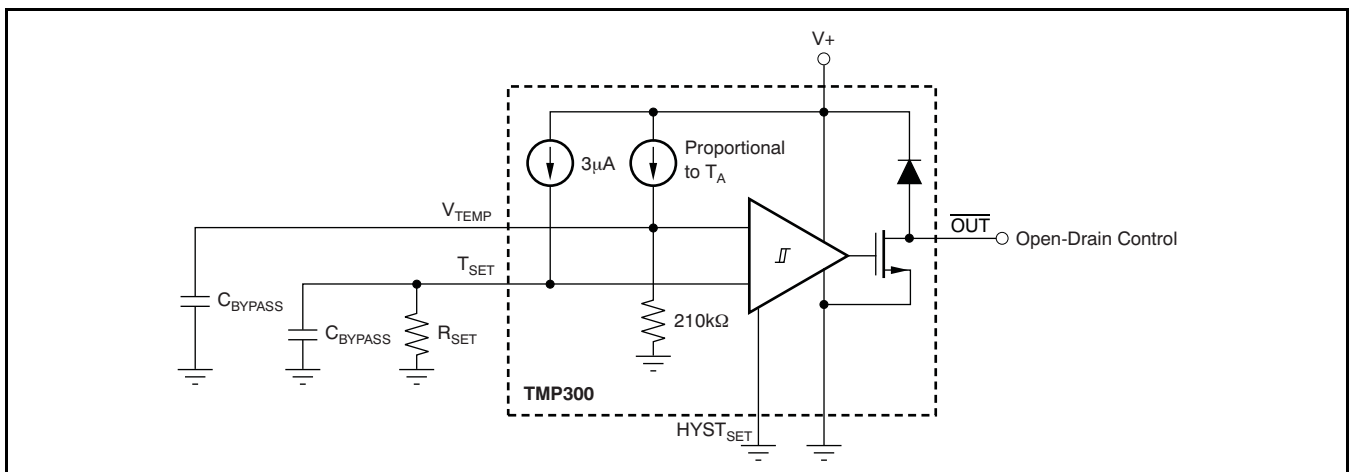


Figure 14. Bypass Capacitors Prevent Early Comparator Toggling Due to Circuit Board Noise

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TMP300BQDCKRQ1	ACTIVE	SC70	DCK	6	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	SBG	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

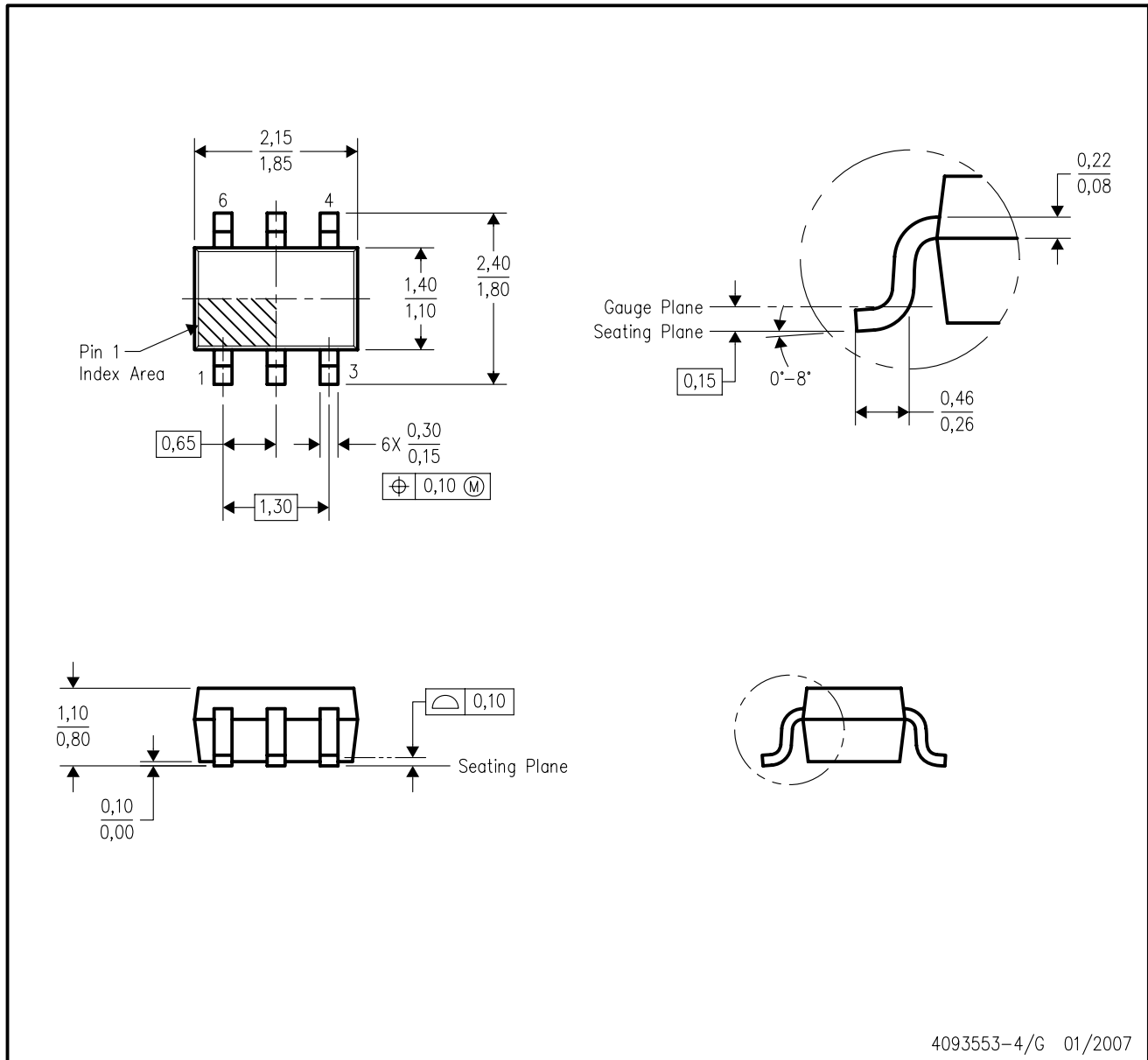
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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DCK (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-203 variation AB.

DCK (R-PDSO-G6)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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